TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (Ultra-High-Speed U-MOSIII)

TPC8212-H

High-Efficiency DC/DC Converter Applications

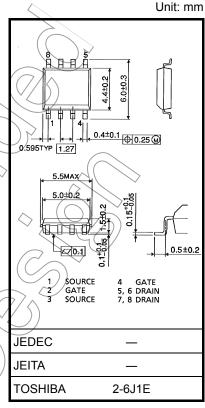
Notebook PC Applications

Portable-Equipment Applications

- Small footprint due to small and thin package
- · High-speed switching
- Small gate charge: Q_{SW} = 5.5 nC (typ.)
- Low drain-source ON-resistance: $R_{DS (ON)} = 16 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: |Y_{fs}| =14 S (typ.)
- Low leakage current: I_{DSS} = 10 μA (max) (V_{DS} = 30 V)
- Enhancement mode: V_{th} = 1.1 to 2.3 V (V_{DS} = 10 V, I_D = 1 mA)

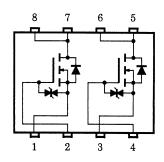
Absolute Maximum Ratings (Ta = 25°C)

Chai	racteristic	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	30	V
Drain-gate voltag	ge (R _{GS} = 20 kΩ)	V_{DGR}	30	V
Gate-source volt	tage	V _{GSS} <	±20	N
Drain current	D C (Note 1)	ID	6	A
	Pulse (Note 1)	IDP)) 24	
Drain power dissipation	Single-device operation (Note 3a)	PD (1)	1.5	
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _D (2)	1.1	//w
Drain power dissipation	Single-device operation (Note 3a)	PD (1)	0.75	<u> </u>
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	P _{D 2)}	0.45	W
Single-pulse avalanche energy (Note 4)		E _{AS}	46.8	mJ
Avalanche currer	nt	IAR.	6	Α
Repetitive avalanche energy (Note 2a, Note 3b, Note 5)		EAR	0.10	mJ
Channel tempera	ature	T _{ch}	150	°C
Storage tempera	ture range	J _{stg}	-55~150	°C



Weight: 0.085 g (typ.)

Circuit Configuration



Note: For Notes 1 to 5, refer to the next page.

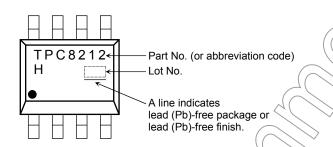
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

Thermal Characteristics

Characteristic		Symbol	Max	Unit
The sweet was interested as a phonon of the combinate	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	83.3	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	125	°C/W
The armed anniate area about a laborate area in	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	167	
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th} (ch-a) (2)	278	

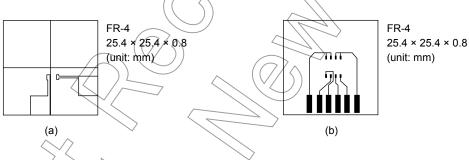
Marking



Note 1: The channel temperature should not exceed 150°C during use

Note 2:

- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)



Note 3:

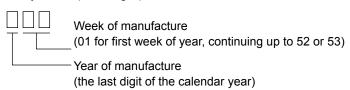
- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)

Note 4: V_{DD} = 24 V, T_{ch} = 25°C (Initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 6.0 A

Note 5: Repetitive rating: pulse width limited by maximum channel temperature

Note 6: • on the lower left of the marking indicates Pin 1.

* Weekly code: (three digits)



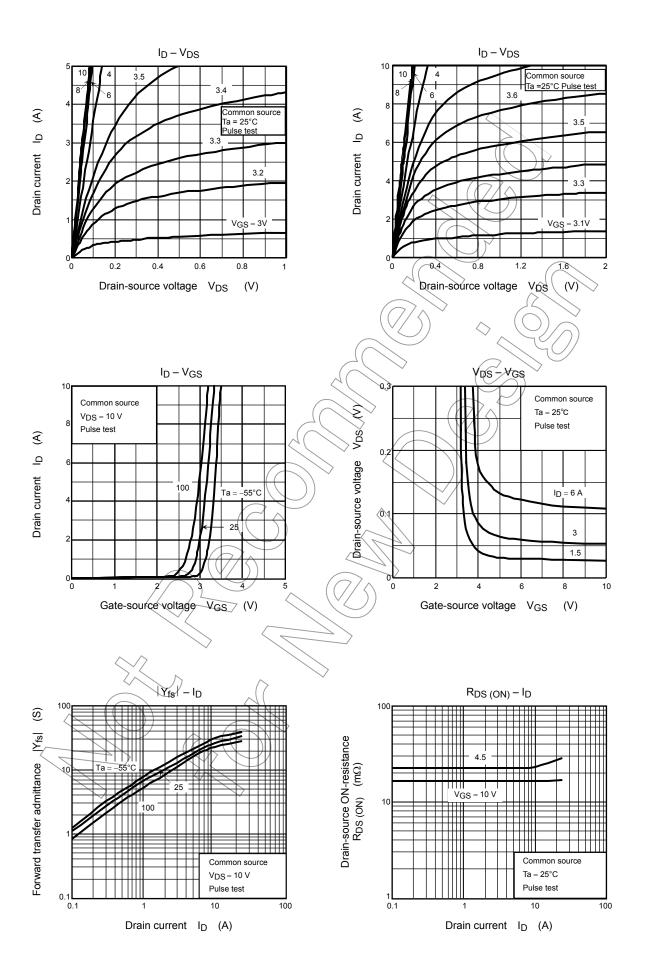
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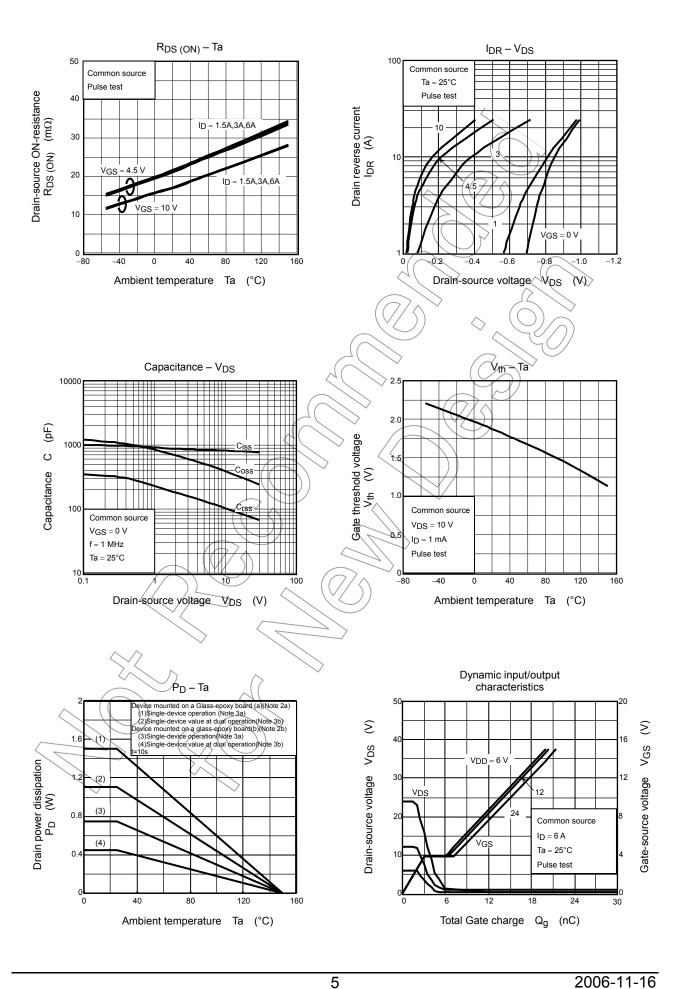
Electrical Characteristics (Ta = 25°C)

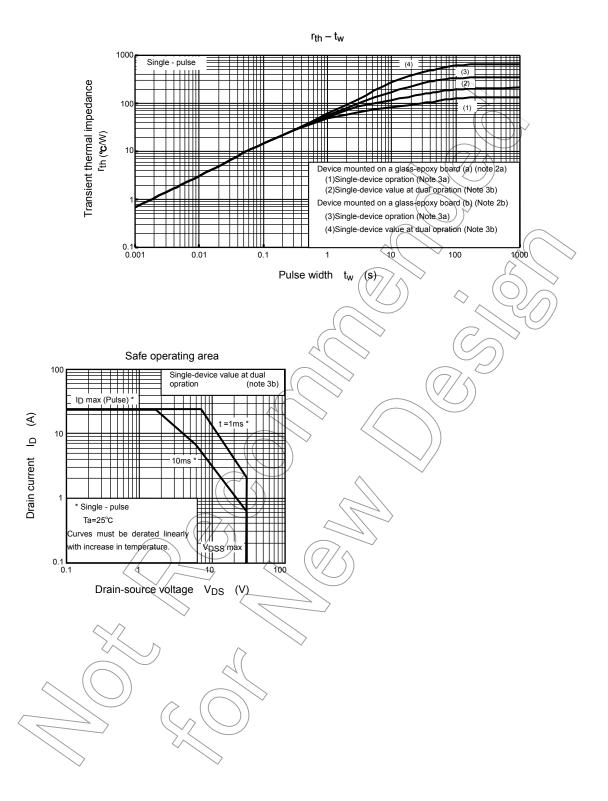
Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μA
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	_	_	10	μΑ
Drain-source breakdown voltage		V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	30	_	_	V
		V (BR) DSX	I _D = 10 mA, V _{GS} = -20 V	15			
Gate threshold	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	7) >_	2.3	V
Drain-source ON-resistance		R _{DS} (ON)	V _{GS} = 4.5 V, I _D = 3 A	\rightarrow	21	27	- mΩ
		R _{DS} (ON)	V _{GS} = 10 V , I _D = 3 A	\rightarrow	16	21	
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V , I _D = 3 A	7	14		S
Input capacitance		C _{iss}			840		
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz.	_	105	/	pF
Output capacitance		Coss		- /	385	\searrow	
Switching time	Rise time	t _r	V_{GS} V_{GS} V_{GS} V_{GS} V_{GS}	(5	> –	
	Turn-on time	t _{on}	$\begin{array}{c c} \text{VOUT} \\ \text{RL} = \\ 5.0 \ \Omega \end{array}$		> 11	_	ns
	Fall time	t _f	4, , , , ,		7	_	115
	Turn-off time	t _{off}	Duty \leq 1%, $t_{\rm W} = 10 \mu{\rm s}$	_	25		
Total gate charge (gate-source plus gate-drain)		Q _g ($V_{DD} = 24 \text{ V}, V_{GS} = 10 \text{ V}, V_{D} = 6 \text{ A}$	_	16	_	
(Note 7)			$V_{DD} \ge 24 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 6 \text{ A}$	_	9	_	
Gate-source charge 1		Q _g s1		_	3.1	_	nC
Gate-drain ("Miller") charge		Qgd	$V_{DD} \simeq 24 \text{ V}, V_{GS} = 10 \text{ V}, D = 6 \text{ A}$	_	4.1	_	
Gate switch charge		Qsw\		_	5.5	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

(1 /					
Characteristic	Symbol Test Condition	Min	Тур.	Max	Unit
Drain reverse current Pulse (Note 1)	I _{DRP} —		_	24	Α
Forward voltage (diode)	V_{DSF} $I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.2	V









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